



AN12030

TEA19031AxT secondary-side SMPS controller

Rev. 1 — 5 October 2017

Application note

Document information

Information	Content
Keywords	TEA19031, SMPS controller, USB-PD, USB Type C
Abstract	The TEA19031 is a secondary side SMPS controller with embedded CoolFlux Digital Signal Processor that supports the USB Power Delivery 2.0 (USB-PD) protocol via a USB Type-C cable connection.



Revision history

Rev	Date	Description
v.1	20171005	first issue

1 Introduction

The TEA19031 is a secondary side SMPS controller with embedded CoolFlux Digital Signal Processor that supports the USB Power Delivery 2.0 (USB-PD) protocol via a USB Type-C cable connection (Ref. 1). Figure 1 shows a typical application diagram. Table 1 provides details about pinning. The TEA19031 forms a link between a connected consumer device and a primary side residing control IC like the TEA193x (Ref. 4). With an optional synchronous rectifier driver like the TEA199x (Ref. 5), the TEA19031 operates the power converter. For communication with the consumer device, Biphasic Mark Coding (BMC) is applied on the Type-C connector CC1 and CC2 lines. Five USB-PD Power Data Objects (PDOs) are supported.

Resulting control and protection information is directed to the primary side controller by adjusting the optocoupler current. Consumer devices requiring output currents exceeding 3 A must either use a captive cable or apply USB-PD e-marking. The TEA19031 does not support the V_{CONN} mechanism, which supplies powered cables.

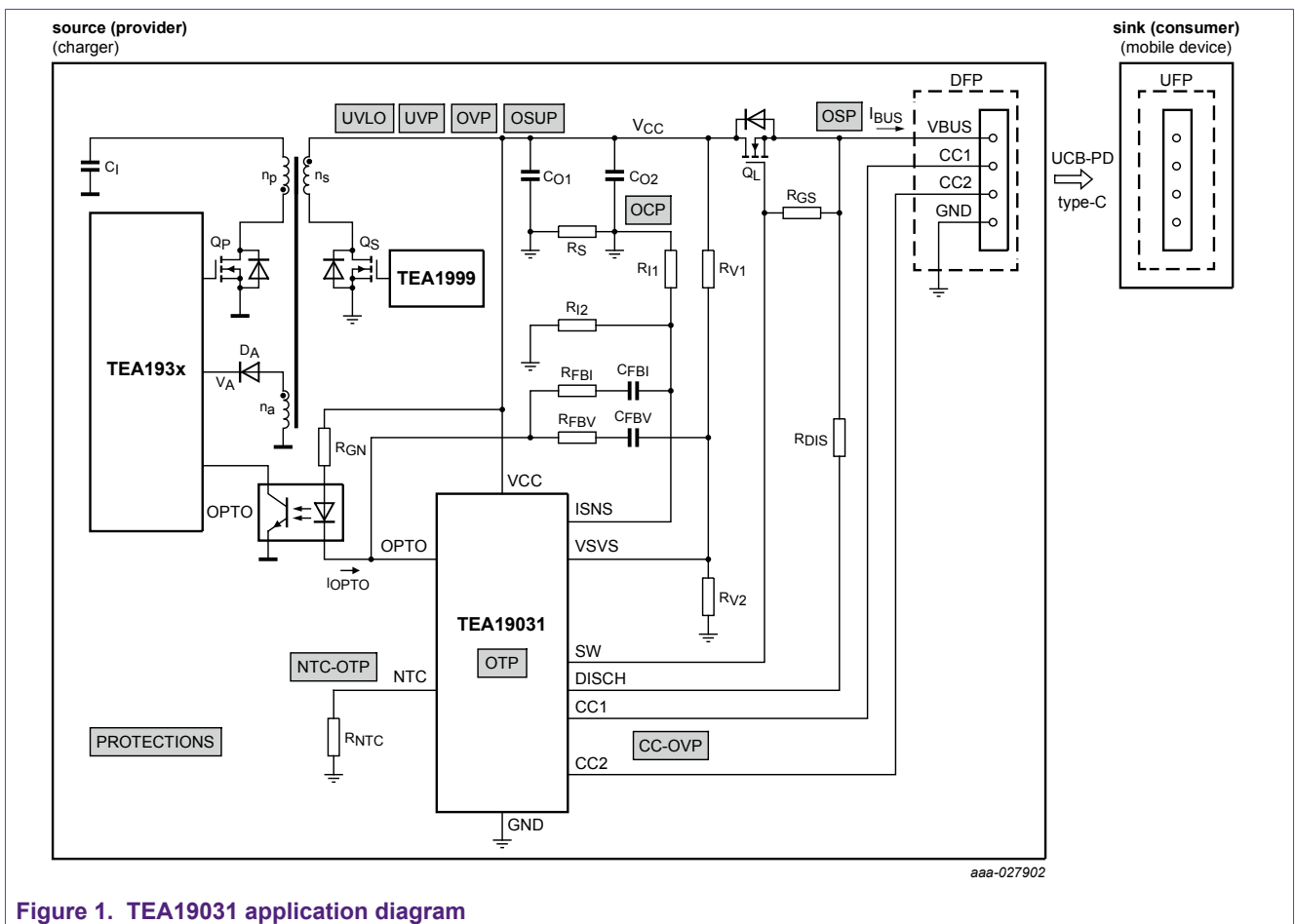


Figure 1. TEA19031 application diagram

Table 1. Pin description

Symbol	Pin	Description
VCC	1	Supply voltage for TEA19031 with internal 20 mA current sink ^[1]
OPTO	2	Optocoupler driver to send control information to primary side power converter controller
NTC	3	External NTC temperature measurement
ISNS	4	Current sense error amplifier input terminal
VSNS	5	Voltage sense error amplifier input terminal
CC2	6	Type-C CC2 detection and USB-PD communication
CC1	7	Type-C CC1 detection and USB-PD communication
DISCH	8	VBUS fast discharge switch and additional internal 1 mA current sink ^[2]
GND	9	ground
SW	10	Load switch (NMOS) driver derived from internally generated boost voltage ^[3]

[1] Active when required for VCC-down regulation (discharge) and overshoot limitation.

[2] Active when both the load switch (QL) and the internal DISCH discharge switch are off.

[3] R_{GS} must be at least 1 MΩ.

A multitude of settings is available, making the TEA19031a versatile device. [Table 2](#) shows an overview of the available TEA19031 variants with their detailed settings. Each variant targets a specific application power level.

Table 2. TEA19031 variant settings

Symbol	Description	AG (18 W)	AD (27 W)	AE (45 W)	AF (60 W)	AM	AO
V _{PDO0} ^[1]	PDO0 voltage vSafe5V (default)	5 V	5 V	5 V	5 V	5 V	5 V
I _{PDO0}	Maximum current for PDO0	3 A	3 A	3 A	3 A	3 A	3 A
V _{PDO1}	PDO1 voltage	5 V	5 V	5 V	5 V	5 V	5 V
I _{PDO1}	Maximum current for PDO1	3 A	3 A	3 A	3 A	3 A	3 A
V _{PDO2}	PDO2 voltage	6 V	6 V	9 V	9 V	9 V	9 V
I _{PDO2}	Maximum current for PDO2	2.9 A	3 A	3 A	3 A	2.49 A	3 A
V _{PDO3}	PDO3 voltage	7 V	7 V	12 V	12 V	12 V	15 V
I _{PDO3}	Maximum current for PDO3	2.5 A	3 A	3 A	3 A	3 A	3 A
V _{PDO4}	PDO4 voltage	8 V	9 V	15 V	15 V	15 V	19 V
I _{PDO4}	Maximum current for PDO4	2.2 A	3 A	3 A	3 A	2 A	3 A
V _{PDO5}	PDO5 voltage	9 V	-	20 V	20 V	-	20 V
I _{PDO5}	Maximum current for PDO5	2 A	-	2.3 A	3 A	-	3.26 A
K _{comp}	cable compensation	117 mV/A	117 mV/A	67 mV/A	67 mV/A	67 mV/A	67 mV/A
K _{Vdiv}	voltage sense resistive divider ratio	1/5.478	1/5.478	1/8.325	1/8.325	1/8.325	1/8.325
R _s	current sense resistor value	5 mΩ	5 mΩ	10 mΩ	10 mΩ	10 mΩ	10 mΩ
CC-OCP	current limiting mode	CC	CC	OCP	OCP	CC	OCP
I _{lim}	limiting current (OCP and CC)	110 %	110 %	120 %	120 %	120 %	120 %

Symbol	Description	AG (18 W)	AD (27 W)	AE (45 W)	AF (60 W)	AM	AO
V _{ovp}	OVP level	120 %	120 %	120 %	120 %	125 %	120 %
NTC	NTC protection	NTC-OCP	NTC-OCP	NTC	NTC	-	-

[1] In addition to the default vSafe5V (VPDO0), five selectable USB-PD PDOs are available

2 USB-PD application

A TEA19031 based application in USB-PD terms consists of a single source (provider) being a mains connected charger and a single sink (consumer) being a mobile device. During start-up, the TEA19031 defaults the VCC converter output voltage to vSafe5V (5 V typical). It limits the current to a fixed maximum of 3 A.

After establishing a valid attach detection, the TEA19031 starts USB-PD contract negotiations by advertising its power capabilities regarding the five PDOs. The consumer responds by requesting one particular PDO. When the TEA19031 in turn accepts this request, the contract is established. It remains in place until the consumer is detached, a hard reset occurs, or the source is unable to maintain its power level.

3 Establishing a type-C connection

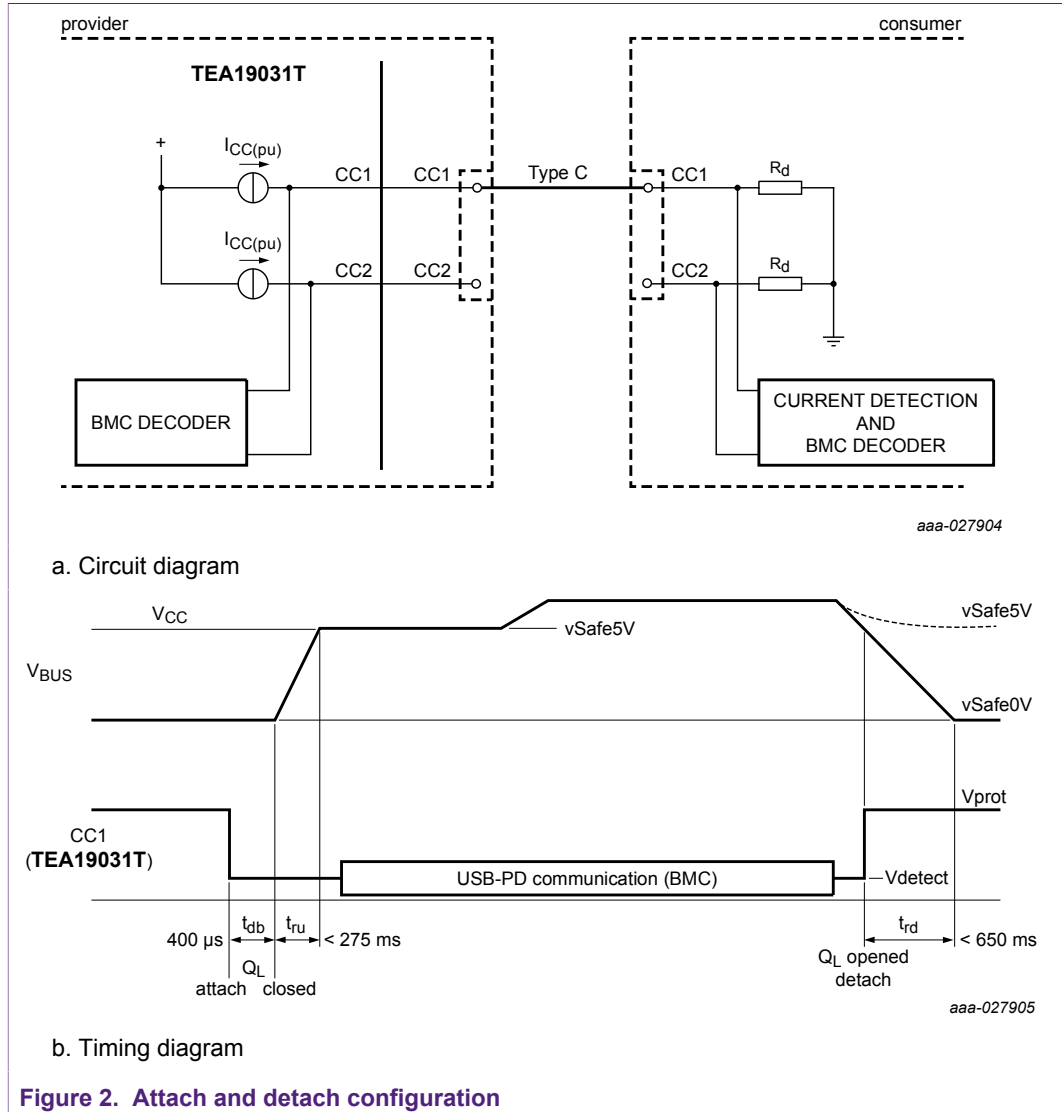


Figure 2. Attach and detach configuration

Equipped with 330 μA pull-up current sources $I_{CC(pu)}$ for each of both CC pins, the TEA19031 advertises the default current capability of the converter at 3 A. A consumer with the appropriate termination resistor R_d (Ref. 2) connected to both CC lines can detect this current capability. At the same time, the TEA19031 detects the attach of a consumer. Figure 2 shows a possible configuration in which the CC1 pin is used by both provider and consumer. Alternatively the CC2 pin can be used.

A typical attach and detach sequence starts with both the provider and consumer being unattached. Load switch Q_L is open and the TEA19031 is waiting to detect the presence of a consumer. Detection starts when a consumer with a pull-down resistor R_d of 5.1 k Ω or 1.1 V voltage clamp is connected to one of the CC lines. Allowing ground offset in the connecting cable, the pull-down resistor or clamp in the consumer must establish a detectable voltage V_{detect} between 0.85 V (V_{IL}) and 2.45 V (V_{IH}) on one of the CC pins of the TEA19031. After a debounce period t_{db} of 400 μs , but while an attached consumer is still detected, load switch Q_L is closed and V_{BUS} is connected to V_{CC} . The internally generated driver voltage on pin SW controls the load switch. This voltage is about 6 V

above V_{CC} . Because of the internal 80 kΩ output resistance of pin SW, the gate-source discharge resistor R_{GS} must be at least 1 MΩ. Within 275 ms, the bus voltage must reach its vSafe5V level such that reliable USB-PD communication can commence. The consumer is now powered. The connected operating state lasts until the TEA19031 detects a detach. Load switch Q_L opens immediately after detecting a detach and the internal switch connected to DISCH discharges V_{bus} through external resistor R_{DISCH} . The V_{bus} voltage level must return to vSafe0V within 650 ms which puts certain design constraints on resistor R_{DIS} and any capacitance connected to V_{bus} . At the same time, the TEA19031 ensures that the V_{CC} level returns to vSafe5V by activating the internal current sink of 20 mA connected to VCC.

As specified in the USB Type-C standard, alternative connection states may be present. Table 3 gives an overview of the various connection states and the corresponding TEA19031 response. In all cases where a sink or Debug Accessory Mode is connected, an attach is detected.

Table 3. USB Type-C connection states and TEA19031 response

State	CC1 connection	CC2 connection	TEA19031 response
nothing attached	open	open	no attach
sink attached	$R_d^{[1]}$	open	attach
	open	$R_d^{[1]}$	attach
powered cable without sink attached	$R_a^{[2]}$	open	no attach
	open	$R_a^{[2]}$	no attach
powered cable with sink attached	$R_d^{[1]}$	$R_a^{[2]}$	attach
	$R_a^{[2]}$	$R_d^{[1]}$	attach
debug accessory mode attached	$R_d^{[1]}$	$R_d^{[1]}$	attach
audio adapter accessory mode attached	$R_a^{[2]}$	$R_a^{[2]}$	

[1] R_d = 5.1 kΩ nominal (alternatively a 1.1 V voltage clamp can be applied) (Ref. 2)

[2] R_a = 1 kΩ nominal (Ref. 2)

4 USB-PD communication

The TEA19031 supports the USB-PD 2.0 standard. The following sections are a limited extraction of the USB-PD standard. However, they never prevail over the USB-PD standard ([Ref. 1](#)).

4.1 Data packets and signaling

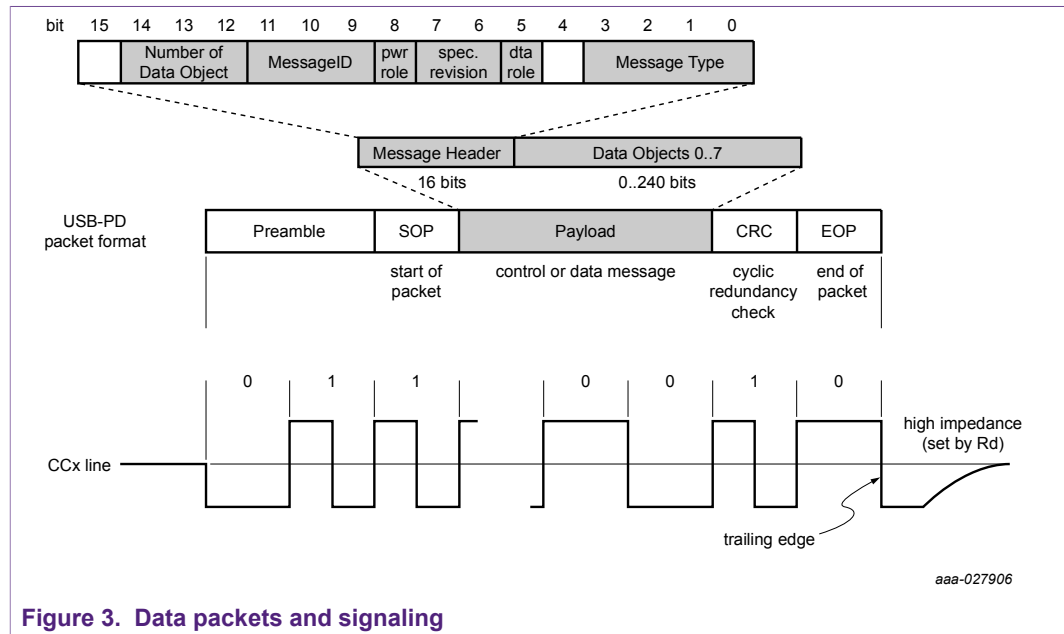


Figure 3 shows the USB-PD messages. They are defined as coded packets that start with a preamble to prepare the receiver for receiving data. The preamble is followed with a Start Of Package (SOP), the actual payload, Cyclic Redundancy Check (CRC) error correction information, and finally an End Of Package (EOP). Two kinds of packet payloads are available:

- Control message:
The payload contains only a message header in which the number of data objects (bits 14 to 12) is zero. The MessageType (bits 3 to 0) identifies the message.
- Data message:
The payload contains a message header. It is followed by one of up to seven data objects; now the number of data objects is non-zero.

Table 4 summarizes the supported USB-PD 2.0 messages. When the TEA19031 receives an unidentified message, it responds with the reject message.

Table 4. USB-PD 2.0 supported messages

MessageType	Packet payload	Send (S)/ Receive (R) ^[1]	Description
GoodCRC	control	S/R	acknowledge that the previous message was correctly received
Accept	control	S/R	source/sink is able meet the Request message
Reject	control	S	source is unable to meet the Request message
PS_RDY	control	S	source indicates that its power supply has reached the desired operating condition
Get_Source_Cap	control	R	sink requests a Source_Capabilities message
Soft_Reset	control	S/R	reset counters to a known state, voltage, and current settings remain unchanged
Source_Capabilities	data	S	source exposes power capabilities with PDOs
Request	data	R	sink response to Source_Capabilities by selecting one advertised PDO

[1] TEA19031 (source) perspective

DC-biased Biphase Mark Code (BMC) is used for signaling the information from transmitter to receiver. BMC is self-clocked. It has at least one polarity change per bit cycle.

- 1 = polarity change at half the bit cycle
- 0 = polarity change to the next bit cycle

A packet starts by driving the active CC line to 0. To ensure that the receiver clocks the last bit before releasing the CC line to return to the DC bias level again, a packet ends with a trailing edge. The consumer pull-down resistor R_d sets the DC bias level. It includes any ground offset due to current flowing through the cable.

4.2 Power data object contract negotiation

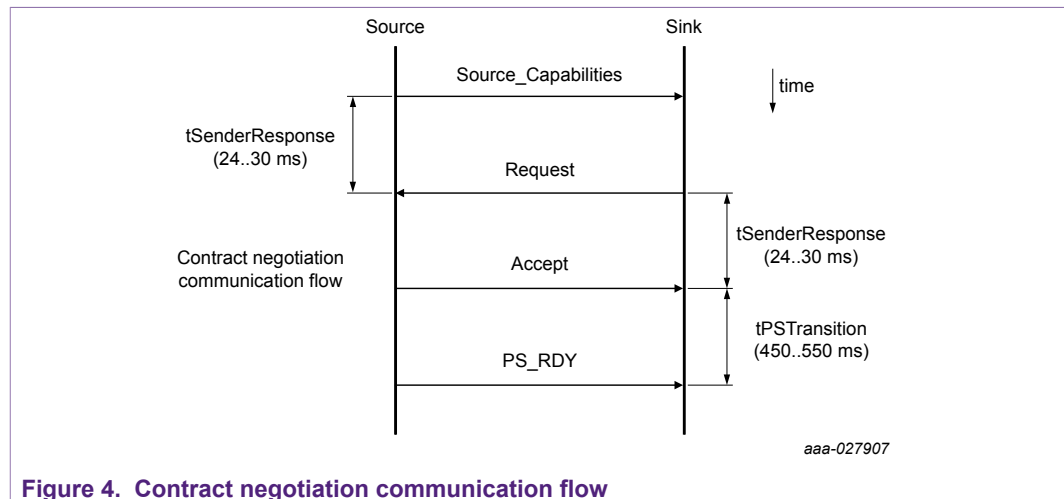


Figure 4. Contract negotiation communication flow

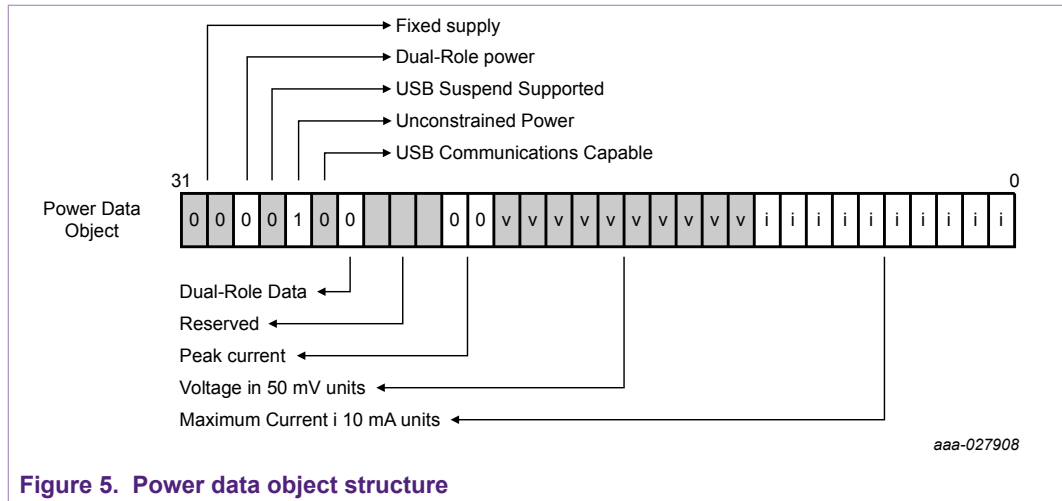


Figure 5. Power data object structure

After establishing a valid connection, USB-PD communication can commence. Figure 4 (a) shows the (explicit) contract negotiation communication flow. The source initiates the negotiations by advertising a Source_Capabilities message. This message starts with a message header followed by five distinct and TEA19031-variant dependent PDOs (see Table 2). Each PDO contains generic information combined with the supported voltage and a maximum current level. Next, the sink selects one of the advertised PDOs and returns a Request message to the source. After validation of the Request message, the source sends an Accept message to the sink. The power control settings are changed in alignment with the request. When V_{bus} has stabilized to the newly requested level, the source sends a PS_RDY message to the sink. The contract has been established.

4.3 Hard reset

Hard reset is a USB-PD-specific ordered set of bytes recognized by the TEA19031. When detected, the result is that load switch Q_L is opened. To bring the converter output voltage (V_{CC}) to $vSafe5V$, the internal current sink connected to V_{CC} is turned on. The internal switch connected to DISCH and external resistor R_{DISCH} discharges the bus voltage (V_{bus}) to $vSafe0V$ for a maximum of 100 ms. Additionally, all internal counters are reset to a known state. To ensure that a new USB-PD communication sequence can start, the connection between producer and consumer remains intact. There is no limit to the number of hard reset attempts.

4.3.1 Converter control

In the power converter application (see Figure 1), the TEA19031 applies Constant-Current Constant-Voltage (CCCV) control. Table 2 shows the detailed characteristics. These characteristics depend on the selected variant.

Internally, the voltage and the current reference levels are changed according to the selected PDO. To achieve the desired output voltage and current levels, some external component values have to match certain criteria. For the appropriate output voltage level, the external resistors R_{V1} and R_{V2} must be selected (see Equation 1).

$$K_{Vdiv} = \frac{R_{V2}}{R_{V1} + R_{V2}} \tag{1}$$

Where:

- $K_{V_{div}}$ is the voltage divider ratio (see [Table 2](#))

Recommended values for the compensation network are

- $R_{V1} = 160\text{ k}\Omega$ to $180\text{ k}\Omega$
- $R_{FBV} = 1\text{ k}\Omega$
- $C_{FBV} = 3.3\text{ nF}$

To achieve the best voltage regulation, resistor R_{V1} must be connected as close as possible to the drain of load switch Q_L . Any track resistance between the drain and resistor R_{V1} results in a voltage offset. For the same reason, resistor R_{V2} must be connected as close as possible to pin GND of the TEA19031. [Figure 6](#) shows the proper connections for voltage sensing.

5 Current sensing and cable compensation

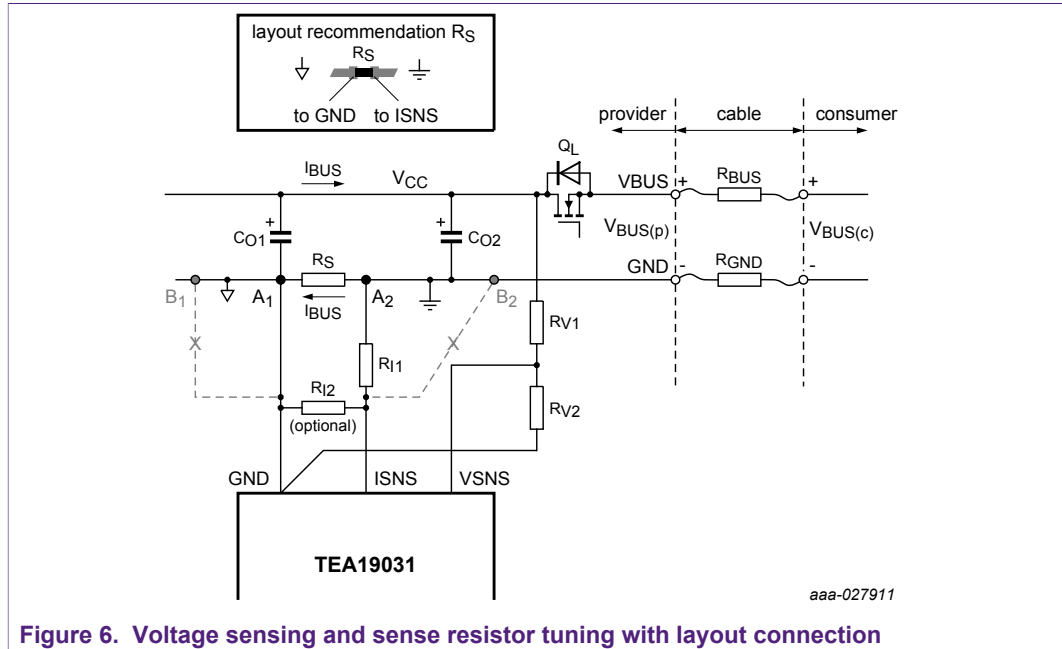


Figure 6. Voltage sensing and sense resistor tuning with layout connection

Output current I_{bus} is measured by sensing the voltage drop over sense resistor R_S . The required sense resistor value is variant-specific. It can be found in [Table 2](#). For the best sensing, it is important to ensure that the TEA19031 sensing PCB tracks are connected close to the terminals of sense resistor R_S . In [Figure 6](#), the A connections are positioned properly. However, the 2 B-connections are positioned poorly. Any voltage drop over the track resistance between the B junctions and the sense resistor terminals introduces measurement errors. The inset shows the recommended layout structure.

An additional resistive divider can be built by adding optional resistor R_{12} . In combination with resistor R_{11} , this divider can be used for adjusting the current measurement.

Recommended values for the compensation network are:

- $R_{11} = 330 \Omega$
- $R_{FBI} = 5 \text{ k}\Omega$ (not mounted when OCP protection applies)
- $C_{FBI} = 100 \text{ nF}$ (not mounted when OCP protection applies)

The parasitic resistance of the USB Type-C cable can cause a substantial voltage drop at high currents between the output of the provider and input of the consumer. The variant-dependent cable compensation implemented in the TEA19031 (partly) compensates this voltage drop and the voltage drop over the channel resistance of Q_L and sense resistor R_S .

$$\begin{aligned}
 V_{bus(c)} &= V_{bus(p)} - (R_{bus} + R_{GND}) \cdot I_{bus} \\
 &= V_{CC} - (R_S + R_{QL} + R_{bus} + R_{GND}) \cdot I_{bus} \\
 &= V_{PDOx} + K_{comp} \cdot I_{bus} - (R_S + R_{QL} + R_{bus} + R_{GND}) \cdot I_{bus}
 \end{aligned} \tag{2}$$

Example:

Operating PDO4 of variant AF at a current of 2 A assuming R_{bus} and R_{GND} including:

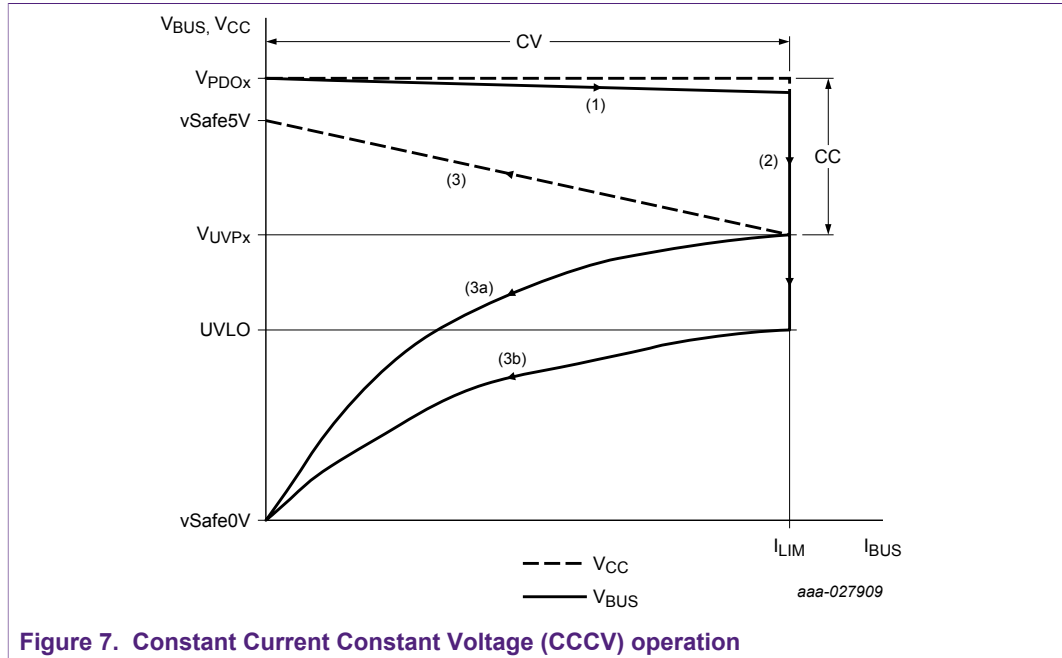
- Contact resistance of the connector = 55 mΩ
- Channel resistance of Q_L = 2.4 mΩ
- Sense resistor R_S = 10 mΩ

The result is a V_{bus} at the consumer input (see [Equation 3](#)).

$$V_{bus(c)} = 15 \text{ V} + 67 \frac{\text{mV}}{\text{A}} \cdot 2 \text{ A} - (10 \text{ m}\Omega + 2.4 \text{ m}\Omega + 55 \text{ m}\Omega + 55 \text{ m}\Omega) \cdot 2 \text{ A} = 14.89 \text{ mV} \tag{3}$$

The result would be 14.76 V without cable compensation.

6 CCCV operation



Constant Current Constant Voltage (CCCV) operation refers to a control methodology with a behavior shown in Figure 7. In region (1), the output voltage (V_{CC}) is regulated to the selected PDO constant voltage level as long as current I_{BUS} drawn by the consumer remains below the selected maximum PDO current (I_{LIM}). Depending on the current level, the bus voltage (V_{BUS}) is slightly lower because of the voltage drop over the internal channel resistance of load switch Q_L and sense resistor R_S . If set to the Constant Current (CC) mode (see Section 8.8), the current is limited to the maximum current when reaching this level. The converter operates under the constant current regime (2). The actual converter behavior now depends on the characteristics of the consumer. If the consumer behaves like a resistor or a voltage sink, the TEA19031 can regulate V_{CC} - and so also V_{BUS} - to a lower voltage level. The lower voltage level balances the current supplied by the source (I_{LIM}) and the current requested by the consumer. This balance can be established as long as the voltage exceeds the UnderVoltage Protection (UVP) or UnderVoltage LockOut (UVLO) level. When the consumer behaves like a current sink, this balance cannot be established. The output voltage immediately drops to the UVP or UVLO level. In either case, load switch Q_L opens and V_{CC} returns to $vSafe5V$ (3). At the same time, V_{BUS} returns to $vSafe0V$ (3a or 3b). If the I_{BUS} current drops to below I_{LIM} before reaching UVP or UVLO, the bus voltage returns to the constant voltage regime (V_{PDOx}).

7 Parabolic slope control

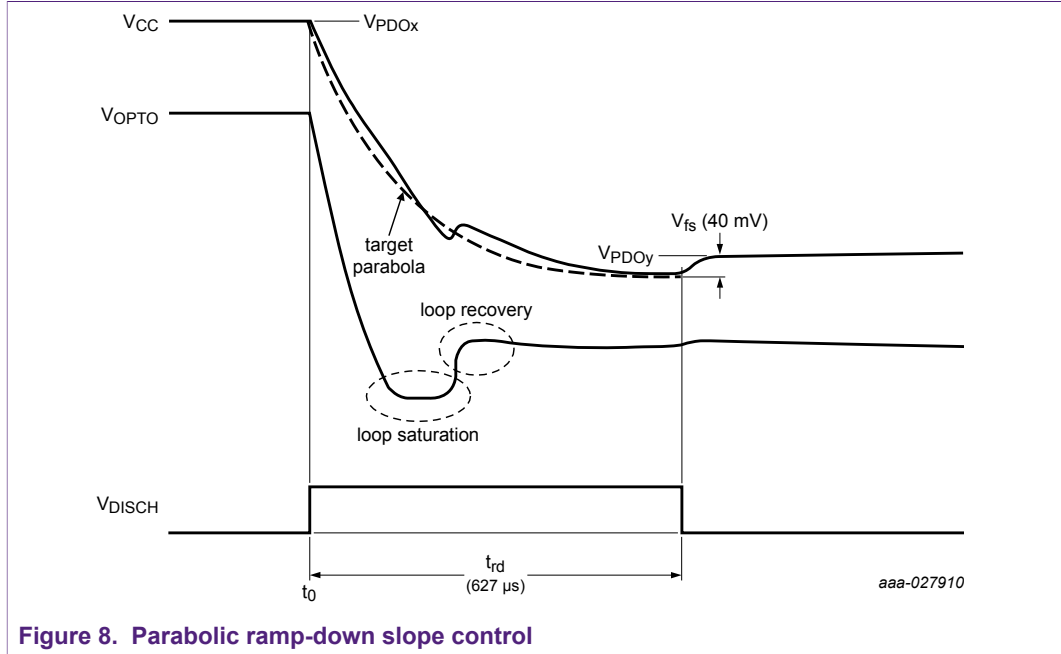


Figure 8. Parabolic ramp-down slope control

Changes in PDO selection during USB-PD communication result in new V_{bus} voltage (V_{PDOx}) and maximum current (I_{PDOx}) settings. The changes in current settings, both up and down, are done in a single step. When the newly requested output voltage level is higher than the currently active one, the TEA19031 changes the set point in a single step. When the primary side controller delivers more power to the output of the converter, the result is a ramp-up. When the new output voltage level is lower than the currently active setting, additional precautions must be taken to ensure that the control loop remains unsaturated at the end of the ramp-down transition period (t_{rd}). If not, any load step directly after the transition can result in an undesired output voltage transient.

To provide the best voltage ramp-down, an advanced parabolic ramp-down algorithm (patent pending) is implemented. The internal discharge switch connected to the DISCH pin is activated. When voltage transition is initiated at t_0 , it provides a discharge current sink. The TEA19031 calculates a parabolic target reference level and regulates the V_{CC} output voltage accordingly. The initial steep slope of the parabola causes the internal voltage error amplifier to saturate. This effect is unavoidable. It results from the external voltage compensation network consisting of R_{FBV} , C_{FBV} , and R_{GN} . The velocity of change in the target parabola slows down progressively and the error amplifier can "catch-up" with the reference level. The best performance is achieved by applying a small 40 mV reference step-up just before reaching the target.

In the ramp-up and ramp-down situations, the TEA19031 sends a PS_RDY signal to the sink immediately after reaching respectively 95 % and 105 % of the new setting. It includes any cable compensation offset described in [Section 5](#).

8 Protections

8.1 Protections overview

[Table 5](#) gives an overview of all available protections. All protections, except UVP, are implemented in hardware, so they are functional under all conditions, even when the internal TEA19031 digital signal processor stalls. When triggered, a protection causes a safe restart with a 1 s repetition interval or a latched response.

Table 5. Overview protections

Protection	Description	Design	Level	Delay	Response
UVLO	undervoltage lockout	hardware	$V_{UVLO(f)}$ (2.8 V) $V_{UVLO(r)}$ (3.0 V)	0 μ s ^[2]	restart
OSP	output short protection	hardware	see UVLO or UVP	-	restart
OVP	overvoltage protection	hardware	V_{ovp} ^{[3][4]}	30 μ s	restart
UVP	undervoltage protection	software	60 % ^{[3][4]}		
OCP	overcurrent protection	hardware	I_{LIM} ^[5]	25 ms	restart
OSUP	open supply protection	hardware	-	0 μ s ^[2]	- ^[6]
CC-OVP	cc-lines overvoltage protection ^[7]	hardware	4.5 V	10 μ s	restart
OTP	overtemperature protection (internal)	hardware	115 °C	0 μ s ^[2]	latched
NTC-OTP	overtemperature protection (external)	hardware	90 °C	0 μ s ^[2]	restart

- [1] See [Table 2](#) for variant-specific settings.
 [2] Immediate response excluding any internal circuit delay.
 [3] As a percentage of the V_{PDOx} level.
 [4] PDO0 and PDO1 have no UVP.
 [5] As a percentage of the I_{PDOx} level.
 [6] V_{CC} supply voltage lost, load switched is opened.
 [7] The active CC attach detection line only.

8.2 Safe-restart response

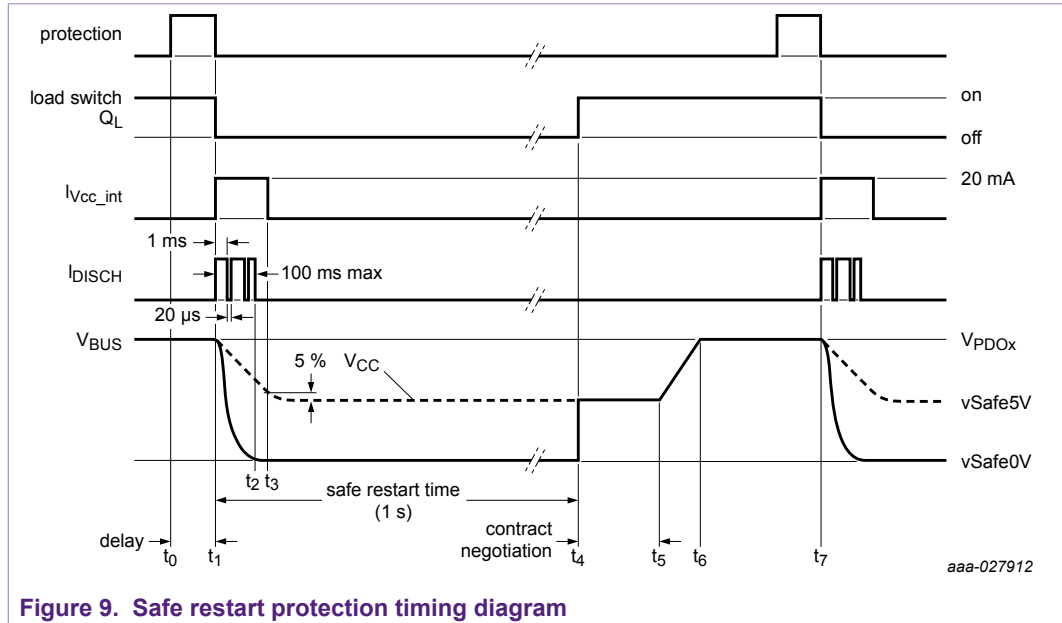


Figure 9. Safe restart protection timing diagram

Figure 9 shows the safe-restart-mode timing diagram. In safe restart mode, load switch Q_L is turned off (t_1) after the protection is triggered (t_0) and expiration of the protection-dependent delay time. The attached consumer is decoupled from the producer. Supported by an internal current sink of typically 20 mA, the TEA19031 error-amplifiers regulate the converter output voltage (V_{CC}) to its vSafe5V level (5 V typical; see the USB-specification (Ref. 1)). The internal current sink remains active until V_{CC} has dropped to below a voltage level of 5 % above the typical vSafe5V level (t_3). The internal switch connected to DISCH is closed. It draws a discharge current from V_{bus} through resistor R_{DISCH} . The voltage on this node drops rapidly. With an interval of 1 ms, the internal DISCH switch opens for a V_{bus} measurement period of 20 μ s. During this period, the TEA19031 samples the bus voltage. Resistor R_{DISCH} and any capacitance connected to the DISCH pin must be designed such that the DISCH pin voltage returns to the V_{bus} level within this measurement period. As long as V_{bus} remains above 0.7 V (maximum 100 ms), the DISCH function remains operational. This mechanism ensures that V_{bus} drops to vSafe0V (t_2) within the appropriate time in alignment with the USB-PD standard.

When triggered, the safe restart timer is started. All circuits are reinitialized. When the 1 s safe-restart time has elapsed (t_4), a new start-up sequence commences. The load switch is closed and the USB-PD contract is negotiated (t_5). After reaching the requested V_{CC} level (t_6), the converter resumes normal operation. If the fault condition persists, the TEA19031 enters a new protection cycle (t_7).

8.3 Latched response

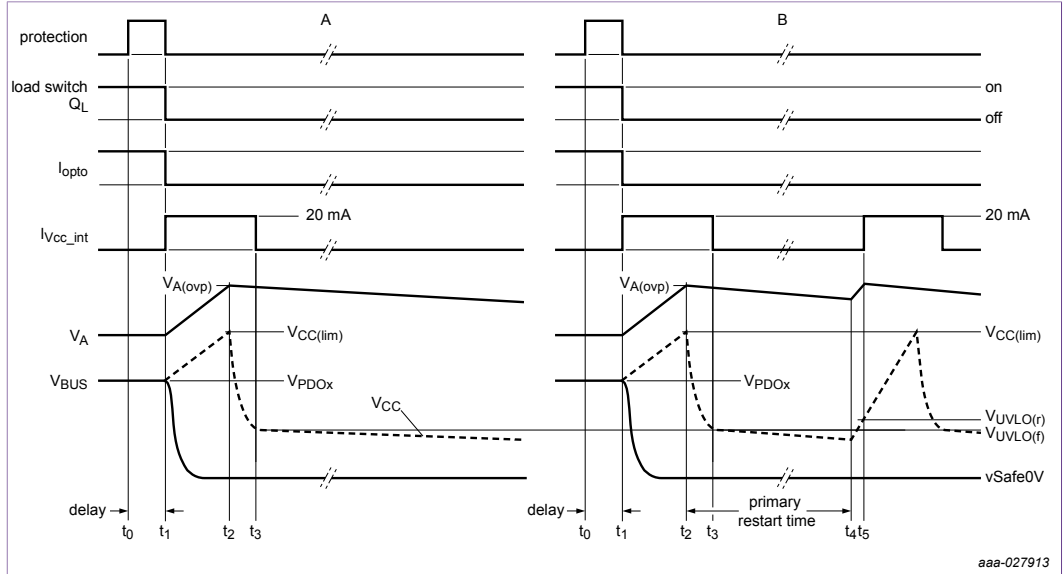


Figure 10. Latched protection timing diagram, primary side latched (A), and primary side induced safe restart (B)

When the actual system is programmed to latched response, its behavior depends on the primary-side controller behavior. Depending on the settings of the primary side controller (Ref. 4), the response is a converter latch (see Figure 10 - A) or yet another primary-side induced save restart (see Figure 10 - B. After triggering of the protection (t_0) and expiration of the protection-dependent delay time, load switch Q_L is turned off (t_1). The attached consumer is decoupled from the producer. An internal current sink current of 20 mA (typical) connected to V_{CC} is activated. At the same time, the optocoupler current is reduced to virtually zero. This zero optocoupler current is an indication for the primary-side controller to increase the amount of power delivered to the output of the converter so V_{CC} increases. The reflected primary-side controller supply voltage (V_A) also increase in alignment with the turns ratio of the transformer. the result is that when the controller supply voltage reaches $V_{A(ovp)}$, the overvoltage protection is triggered on the primary side (t_2). The primary-side controller stops operation of the converter. V_{CC} gradually drops to below the falling UVLO level ($V_{UVLO(f)}$) because of the TEA19031 internal current sink. If there is a primary-side latched protection, the converter remains off. When a primary-side induced safe restart is programmed, the primary-side controller initiates a new start-up cycle (t_4). As soon as V_{CC} crosses the rising UVLO level $V_{UVLO(r)}$, the internal current sink is turned on again (t_5). The load switch remains off and the optocoupler current remains zero. This sequence repeats itself continuously. The maximum V_{CC} voltage can be calculated with Equation 4. Load switch Q_L must be able to withstand this $V_{CC(lim)}$ voltage.

$$V_{CC(lim)} = \frac{n_s}{n_a} \cdot V_{A(ovp)} \tag{4}$$

Where:

- If a protection latches the converter $V_{CC(lim)}$ is the maximum VCC voltage
- n_s is the number of secondary turns on the transformer
- n_a is the number of primary-side controller supply turns on the transformer
- $V_{A(ovp)}$ is the OVP level of the primary-side controller supply voltage ([Ref. 4](#))

8.4 UnderVoltage LockOut (UVLO)

In order to assure well-defined internal TEA19031 functionality and proper driving of load switch Q_L , all circuits are released only when V_{CC} rises above $V_{UVLO(r)}$. A protection is triggered when V_{CC} drops below $V_{UVLO(f)}$ again. This situation can occur when the connected consumer draws too much current I_{BUS} while operating in Constant Current (CC) mode (see [Section 8.8](#)). It can also occur when any other protection has triggered a latched response. The protection is implemented in hardware with fixed levels.

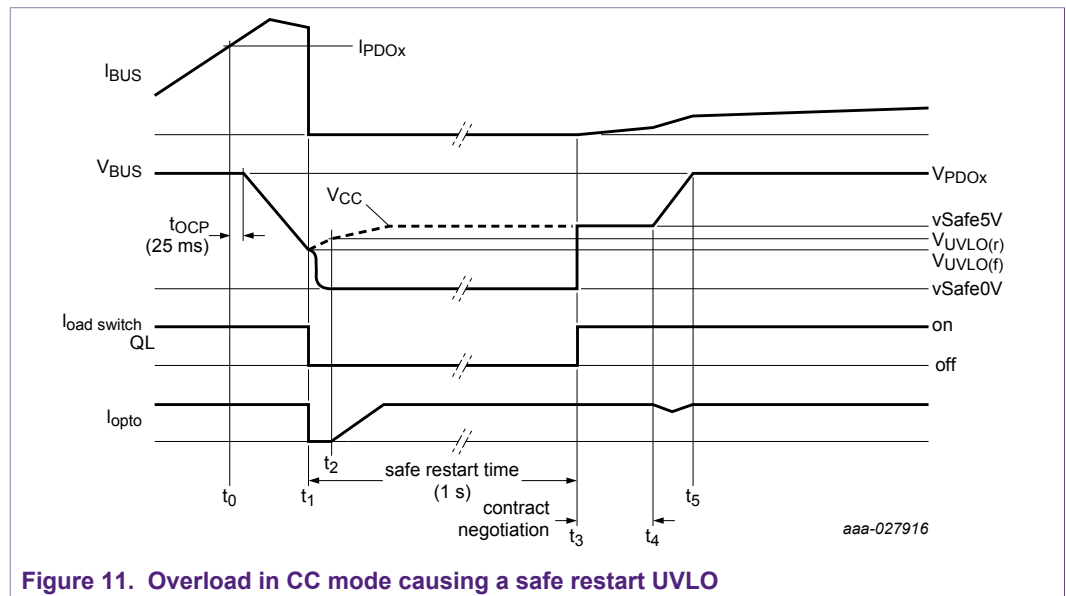


Figure 11. Overload in CC mode causing a safe restart UVLO

Figure 11 shows an overload on V_{bus} in CC mode, which causes V_{CC} to drop out of regulation. A safe restart UVLO protection is triggered. The optocoupler current remains constant because of the constant current control action of the TEA19031. V_{CC} continues to drop. When the voltage drops to below $V_{UVLO(f)}$, the load switch is opened immediately. It disconnects the consumer from the converter (t_1). With the load disconnected and the primary side delivering full power, V_{CC} increases again. When V_{CC} exceeds $V_{UVLO(r)}$ (t_2), the TEA19031 regulates the output voltage to v_{Safe5V} . After the 1 s safe restart time has elapsed, the load switch closes again (t_3). The controller awaits new contract negotiations. These negotiations must be concluded (t_4) before regulation can continue toward the final V_{PD0x} level (t_5). If the overload condition still persists, the converter enters a new safe-restart cycle.

8.5 Output Short Protection (OSP)

Short circuit is a special case of overload. UVLO and UVP protect against short circuits. A short circuit can occur during operation or prior to the converter start-up. In both cases, when the load switch is closed, the current drawn from V_{CC} increases rapidly. To endure this condition, the selection of the load switch must handle worst case energy dissipation (see Equation 5) until the switch opens after the UVLO protection is triggered. The PCB tracks must sustain the corresponding high current determined by the total impedance of the load switch channel resistance, sense resistor R_S , and any PCB track resistance. Careful layout must ensure that, when the load switch is turned off while carrying this high current, load switch drain does not suffer from an inductive voltage spike. Similarly, a negative voltage may be induced at the source of the load switch. To avoid inductive turn-on of the load switch, which could be detrimental for the converter, this voltage must be restrained.

$$E_{QL(max)} = \frac{1}{2} \cdot C_O \cdot (V_{CC(0)}^2 - V_{UVLO(f)}^2) \tag{5}$$

Where:

- $E_{QL(max)}$ is the maximum energy to be dissipated in the load switch
- C_O is the total output capacitance connected to V_{CC}
- $V_{CC(0)}$ is the V_{CC} voltage when the short circuit happens and equals V_{PDOx}

Figure 12 shows a measured waveform of a short-circuit occurrence. The maximum current increases rapidly and a sharp voltage spike can be observed on V_{CC} . The source of Q_L (V_{bus}) briefly dips to a negative level. However, it does not drop deep enough to turn on the switch again, which is undesired.

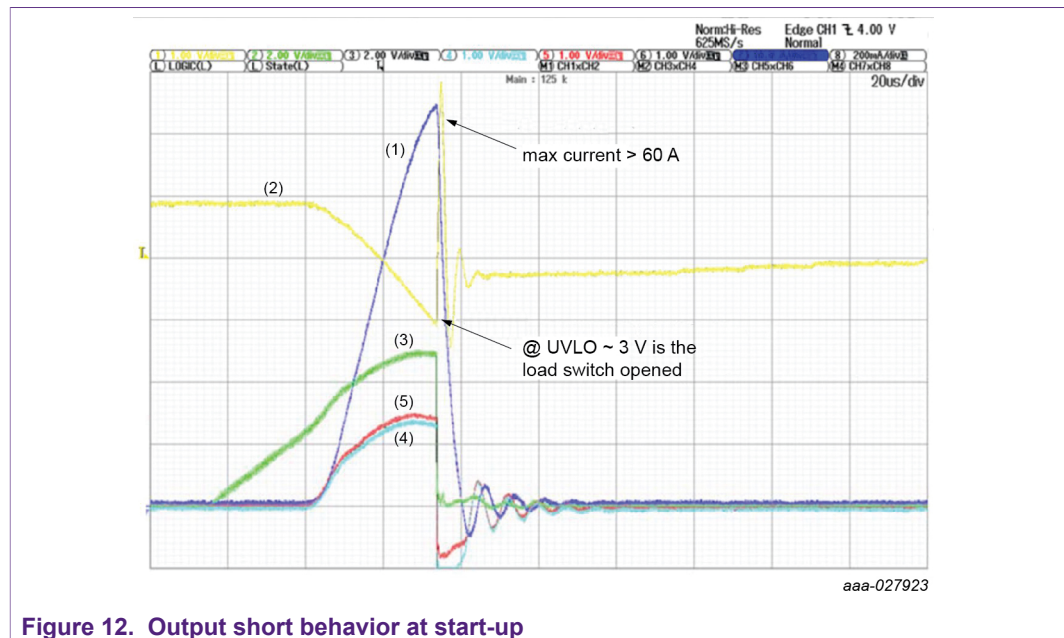


Figure 12. Output short behavior at start-up

The TEA19031 pin voltages must never exceed the absolute maximum ratings as specified in the TEA19031 data sheet (Ref. 3).

8.6 OverVoltage Protection (OVP)

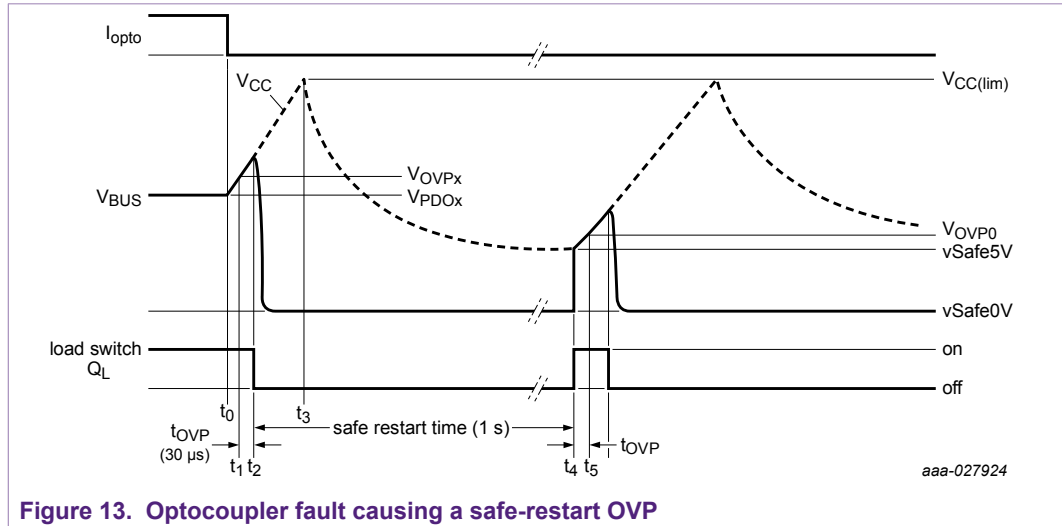


Figure 13. Optocoupler fault causing a safe-restart OVP

If the optocoupler feedback path to the primary side controller gets disrupted, the OVP, measured on pin VCC, prevents further damage to the consumer by opening load switch Q_L. Figure 13 shows an example of the OVP sequence with safe-restart response. At t_0 , the optocoupler unexpectedly ceases to conduct current due to a fault condition. Although V_{CC} and V_{bus} are programmed at V_{PDOx}, both voltages start to increase. When V_{CC} reaches the corresponding protection trip level at V_{OVpx} (t_1) and after a 30 μ s blanking time (t_{OVP} ; t_2), the load switch opens. The bus voltage rapidly drops to vSafe0V. However, V_{CC} increases to V_{CC(lim)} (t_3), which depends on the primary OVP voltage (see Equation 4). When the 1 s safe-restart timer has elapsed, a new safe-restart attempt is made. Before any USB-PD communication has taken place, the control and protection levels are reset to V_{PDO0}, which is equivalent to vSafe5V. It means that the new OVP trip level is at V_{OVp}. It is related to vSafe5V. If the optocoupler fault condition persists, a new safe restart cycle starts at t_5 .

8.7 UnderVoltage Protection (UVP)

When the output voltage drops too much during an overload condition, an additional UVP protection level, measured on pin VCC, can be triggered. For all PDOs except PDO0 and PDO1, this UVP level is at 60 % of the programmed V_{PDOx} level. When V_{CC} reaches UVP, a safe-restart response follows. PDO0 and PDO1 have no UVP. They rely on the UVLO protection.

8.8 OverCurrent Protection (OCP)

When the consumer draws a current that exceeds the limiting current level (I_{lim}), the TEA19031 allows the power converter to operate in CC mode or to respond with an OCP. The limiting current level is variant-dependent (see Table 2). For details on CC-mode operation and protection, see Section 6 and Section 8.4. Figure 14 shows the timing sequence when OCP is active.

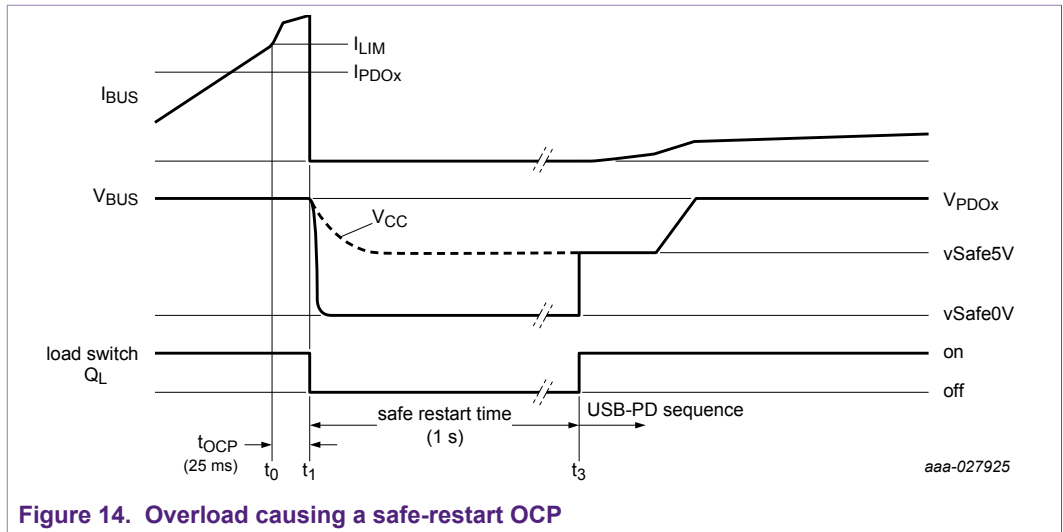


Figure 14. Overload causing a safe-restart OCP

When a current exceeding the limiting current (I_{lim}) triggers OCP, the protection sequence is initiated (t_0). The protection only becomes effective after t_{OCP} (25 ms) at t_1 . Load switch Q_L is opened. V_{CC} is regulated to the vSafe5V level. V_{BUS} drops to the vSafe0V level. OCP results in a safe restart. So, after the safe-restart timer has elapsed, a new USB-PD initiation cycle commences (t_3).

8.9 Open-Supply Protection (OSUP)

To ensure unconditional protection of the consumer, the TEA19031 uses the available voltage on the OPTO pin to turn off load switch Q_L immediately if there is an unexpected supply voltage (V_{CC}) failure. When V_{CC} is restored, the controller resumes normal operation.

8.10 Internal OverTemperature Protection (OTP)

If the internal TEA19031 temperature exceeds 115 °C, a latched protection is triggered (see [Section 8.3](#)).

8.11 NTC thermal protection (external OTP)

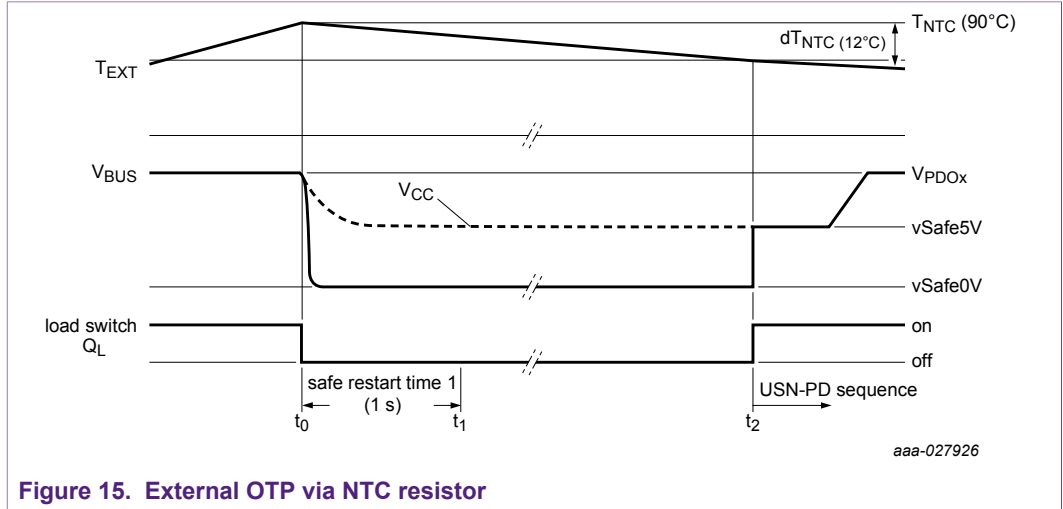


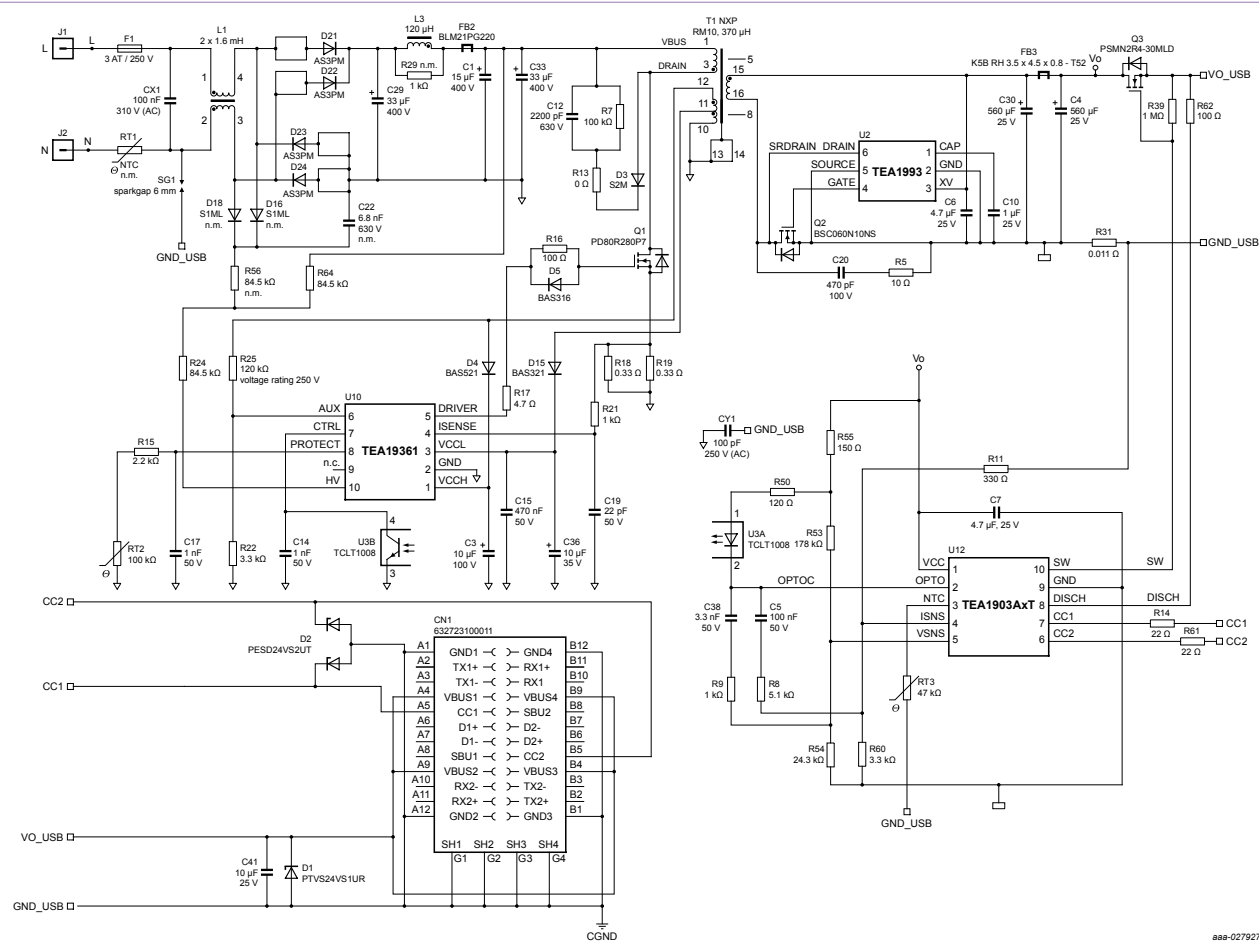
Figure 15. External OTP via NTC resistor

In addition to the internal temperature protection, an external temperature protection is available via the NTC pin. A 47 kΩ NTC resistor with a β-constant of 4050 (e.g. EPCOS B57321V2473J060 or Murata NCU18WB473F60RB) must be connected to the NTC pin of the TEA19031. When the external temperature exceeds the NTC-OTP trip level of 90 °C (t_0), a safe restart is initiated. When the safe restart timer has elapsed (t_1) and while the external temperature remains above 78 °C, the TEA19031 suspends converter start-up. When the external temperature drops to below this lower temperature boundary (t_2), the TEA19031 releases the converter for a new USB-PD communication sequence. At this lower temperature level, the NTC value has decreased to about 4 kΩ.

8.12 Communication interface protection

Immediately after attach detection, the active CC detection line is overvoltage protected at 4.5 V. When the protection is triggered, a safe-restart cycle is initiated. The second CC line is not protected.

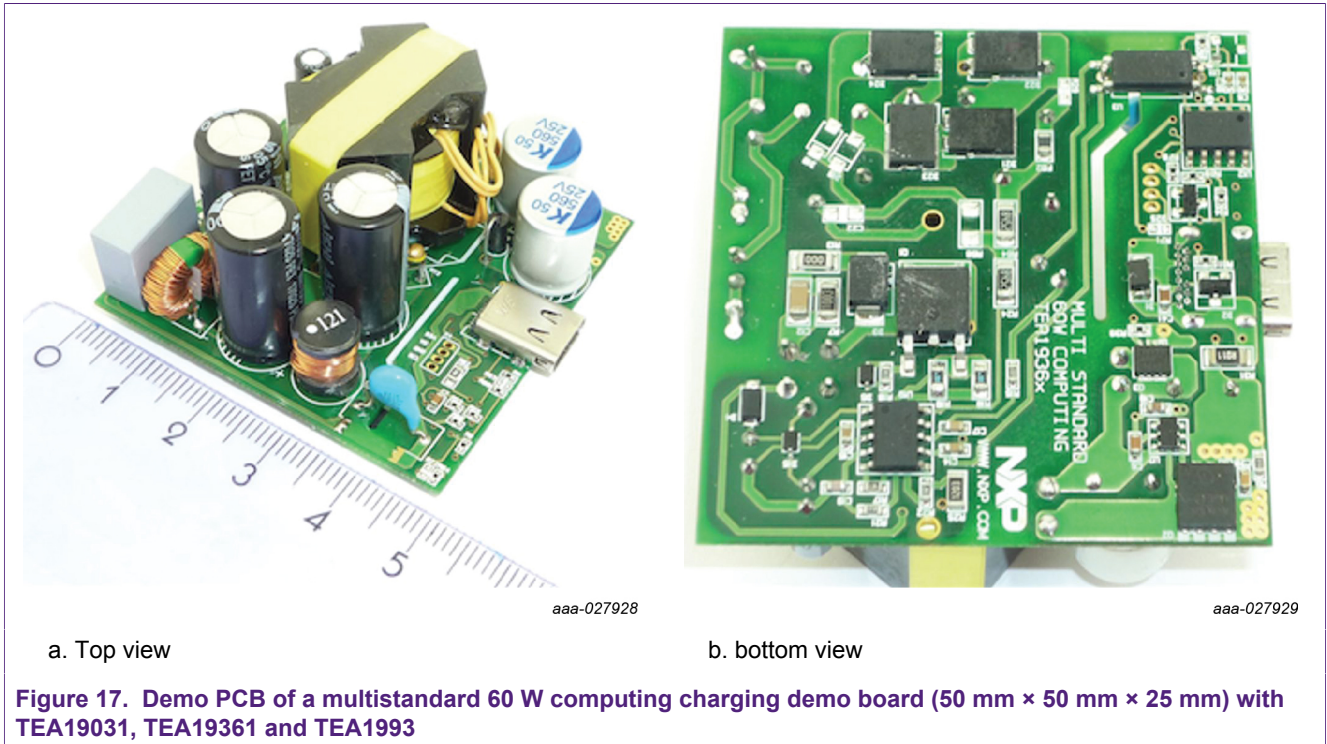
9 Application diagram



aaa-027927

Figure 16. Circuit diagram of multistandard 60 W computing charging demo board with TEA19031, TEA19361, and TEA1993

10 Printed-Circuit Board (PCB) demo



11 Abbreviations

Acronym	Description
BMC	Biphase Mark Code
CCM	Constant Current Mode
CCCV	Constant-Current Constant-Voltage
CC-OVP	CC-lines OverVoltage Protection
CRC	Cyclic Redundancy Check
DFP	Down-stream Facing Port ^[1]
EOP	End Of Packet
NTC	Negative Temperature Coefficient
OCP	OverCurrent Protection
OSP	Output Short Protection
OSUP	Open-SUPply Protection
OTP	OverTemperature Protection
OVP	OverVoltage Protection
PDO	Power Data Object
SMPS	Switched-Mode Power Supply
SOP	Start Of Packet
UFP	Upstream Facing Port ^[2]
USB-PD	USB Power Delivery (Ref. 1)
UVLO	UnderVoltage LockOut
UVP	UnderVoltage Protection
vSafe0V	Safe operating voltage at 0 V ^[3]
vSafe5V	Safe operating voltage at 5 V ^[4]

[1] DFP indicates the position of the port in the USB topology, typically corresponding to a USB host root port or hub downstream port as defined in USB Type-C ([Ref. 2](#)).

[2] UFP indicates the position of the port in the USB topology, typically a port on a device as defined in USB Type-C ([Ref. 2](#)).

[3] $0\text{ V} \leq v_{\text{Safe0V}} \leq 0.8\text{ V}$.

[4] $4.75\text{ V} \leq v_{\text{Safe5V}} \leq 5.5\text{ V}$.

12 References

1	USB Power Delivery Specification	Rev. 2.0 Version 1.3; January 12, 2017
2	USB Type-C Cable and Connector Specification	Revision 1.2; March 25, 2016 and ECNs
3	TEA19031 data sheet	USB-PD controller for SMPS; 2017, NXP Semiconductors
4	TEA193x data sheets	GreenChip primary-side control IC; 2016/2017, NXP Semiconductors
5	TEA199x data sheets	GreenChip synchronous rectifier controller; 2016/2017, NXP Semiconductors

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Date of release: 5 October 2017
Document identifier: AN12030